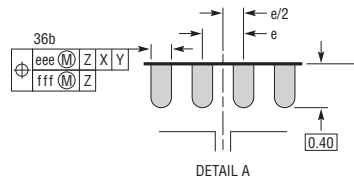
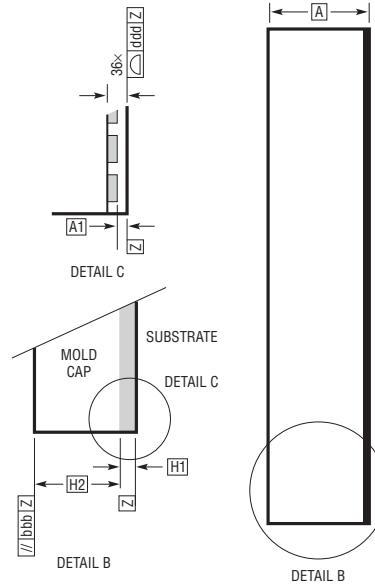
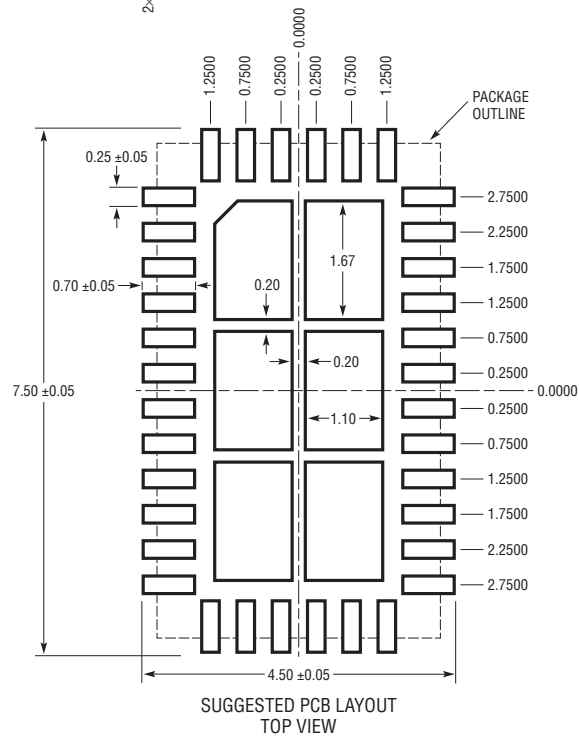
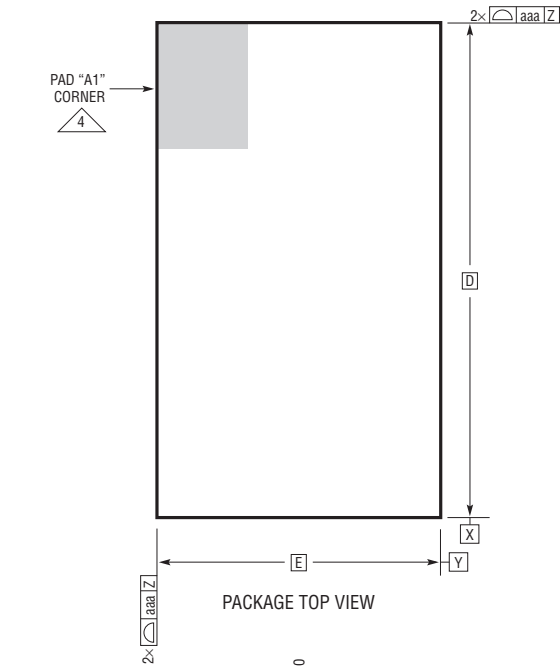
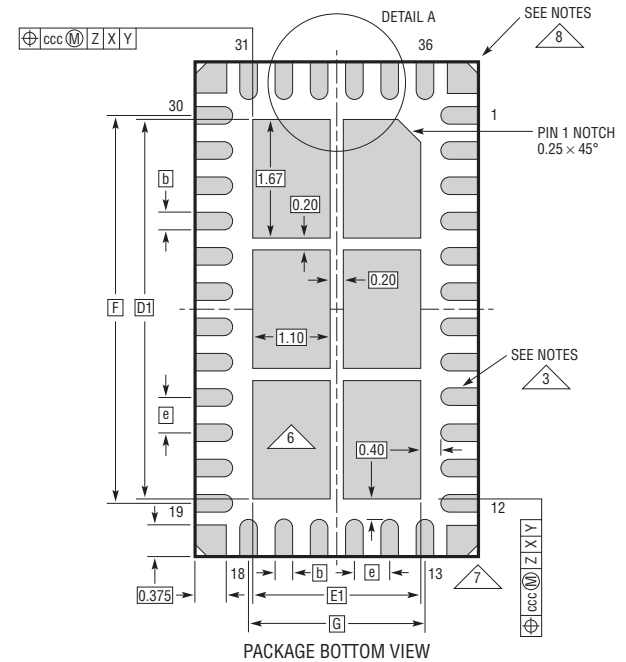


LGA Package
36-Lead (7mm × 4mm × 0.94mm)
 (Reference LTC DWG # 05-08-1525 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	0.85	0.94	1.03	
A1	0.01	0.02	0.03	
b	0.22	0.25	0.28	
D		7.00		
E		4.00		
e		0.50		
F		5.50		
G		2.50		
D1		5.40		
E1		2.40		
H1	0.20	0.24	0.28	
H2	0.65	0.70	0.75	
aaa			0.10	
bbb			0.10	
ccc			0.08	
ddd			0.10	
eee			0.15	
fff			0.08	



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. METAL FEATURES UNDER THE SOLDER MASK OPENING NOT SHOWN SO AS NOT TO OBSCURE THESE TERMINALS AND HEAT FEATURES
 4. DETAILS OF PAD #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PAD #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. THE EXPOSED HEAT FEATURE IS SEGMENTED AND ARRANGED IN A MATRIX FORMAT. IT MAY HAVE OPTIONAL CORNER RADII ON EACH SEGMENT
 7. CORNER SUPPORT PAD CHAMFER IS OPTIONAL
 8. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

